TOSHIBA Field Effect Transistor Silicon N, P Channel MOS Type (π-MOSVI/U-MOSII)

TPC8402

Lithium Ion Secondary Battery Applications Notebook PCs Portable Equipment Applications

• Low drain-source ON resistance

: P Channel RDS (ON) = 27 m Ω (typ.) N Channel RDS (ON) = 37 m Ω (typ.)

High forward transfer admittance

ingn forward transfer admittance : P Channel $|Y_{fs}| = 7 S \text{ (typ.)}$

N Channel $|Y_{fs}| = 6 S \text{ (typ.)}$

• Low leakage current

: P Channel IDSS = $-10 \mu A (VDS = -30 V)$

N Channel IDSS = $10 \mu A \text{ (VDS} = 30 \text{ V)}$

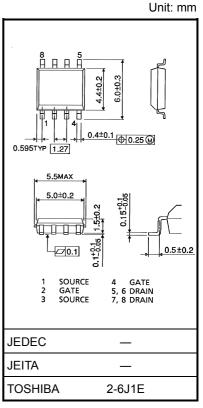
• Enhancement-mode

: P Channel $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{mA})$

N Channel $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{mA})$

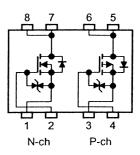
Maximum Ratings (Ta = 25°C)

	0	Rat					
С	Symbol	P Channel	N Channel	Unit			
Drain-source v	roltage	V_{DSS}	-30	30	V		
Drain-gate vol	tage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	-30	30	V		
Gate-source v	oltage	V _{GSS}	±20	±20	V		
Drain current	DC (Note 1)	I _D	-4.5	5	Α		
Dialii Cuitelii	Pulse (Note 1)	I _{DP}	-18	20	ζ		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.5	1.5			
(t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.0	1.0	W		
Drain power dissipation			0.75	0.75	VV		
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45	0.45			
Single pulse a	E _{AS}	26.3 (Note 4a)	32.5 (Note 4b)	mJ			
Avalanche cur	I _{AR}	-4.5	5	Α			
Repetitive ava Single-device	E _{AR}	0.10		mJ			
Channel temp	T _{ch}	150		°C			
Storage tempe	Storage temperature range			-55~150			



Weight: 0.080 g (typ.)

Circuit Configuration



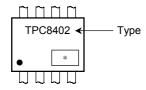
Note: For (Note 1), (Note 2a), (Note 2b), (Note 3a), (Note 3b), (Note 4a), (Note 4b) and (Note 5), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3	
	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	125	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	°C/W
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	278	

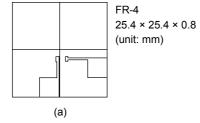
Marking

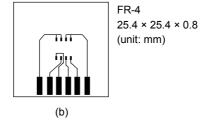


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)





Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4:

- a) $V_{DD} = -24 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (Initial), L = 1.0 mH, $R_G = 25 \Omega$, $I_{AR} = -4.5 \text{ A}$
- b) $V_{DD} = 24 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (Initial), L = 1.0 mH, $R_{G} = 25 \Omega$, $I_{AR} = 5.0 \text{ A}$

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6: • on lower left of the marking indicates Pin 1.

* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

P-0ch

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-OFF current		I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	_	_	-10	μA
Drain-source br	eakdown voltage	V _{(BR) DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Dialit Source bi	eakdown voltage	V _{(BR)DSX}	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15	_	_	V
Gate threshold	voltage	V_{th}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source O	N resistance	R _{DS (ON)}	$V_{GS} = -4 \text{ V}, I_D = -2.2 \text{ A}$	1	55	65	mΩ
Dialii-source O	in resistance	R _{DS (ON)}	$V_{GS} = -10 \text{ V}, I_D = -2.2 \text{ A}$	_	27	35	11122
Forward transfe	r admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.2 \text{ A}$	3.5	7	_	S
Input capacitance		C _{iss}		_	970	_	
Reverse transfer capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	180	_	pF
Output capacita	nce	Coss			370	_	
	Rise time	t _r	V_{GS} $\stackrel{0}{\underset{-10}{\text{V}}}$ $\stackrel{I_{D}=-2.2 \text{ A}}{\underset{VOLUE}{\overset{\circ}{\underset{-10}{\text{V}}}}}$	_	17	_	
Cuitabina tima	Turn-ON time	t _{on}	I V V V V V V V V V	_	20	_	20
Switching time	Fall time	t _f		_	75	_	ns
	Turn-OFF time	t _{off}	$V_{ m DD} = -15 m V$ Duty $\leq 1\%$, $t_{ m W} = 10 \mu m s$	_	160	_	
Total gate charge (Gate-source plus gate-drain)		Qg			28	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -4.5 \text{ A}$	_	6	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	12	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-18	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = -4.5 A, V _{GS} = 0 V	_	_	1.2	V

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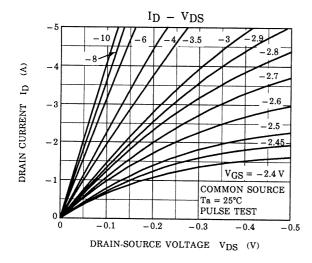
Electrical Characteristics (Ta = 25°C)

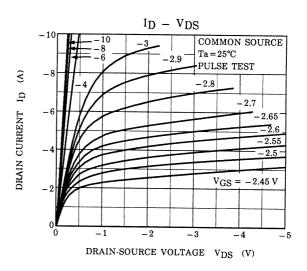
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-OFF	current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	10	μΑ
Drain-source breakdown voltage		V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_	_	٧
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 4 V, I _D = 2.5 A	1	58	80	mΩ
Dialii-source O	iv resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.5 A	1	37	50	mΩ
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	3	6	_	S
Input capacitano	e	C _{iss}		_	475	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	85	_	pF
Output capacita	nce	C _{oss}		_	270	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10 \text{ V}}{_{0 \text{ V}}} \prod \qquad \stackrel{I_{D} = 2.5 \text{ A}}{\underset{V_{OUTD}}{\longrightarrow}}$	_	10	_	
	Turn-ON time	t _{on}	$\begin{array}{c c} & \text{VOUT} \\ & \text{RL} = \\ & 6 \Omega \end{array}$	_	16	_	ns
	Fall time	t _f	$\begin{array}{c c} V_{DD} = 15 \text{ V} \end{array}$	ı	13	_	113
	Turn-OFF time	t _{off}	Duty \leq 1%, $t_{\rm W} = 10 \ \mu \rm s$	1	70	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	16	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \approx 24 \text{ V, } V_{GS} = 10 \text{ V, } I_D = 5 \text{ A}$		11	_	nC
Gate-drain ("miller") charge		Q_{gd}		_	5	_	

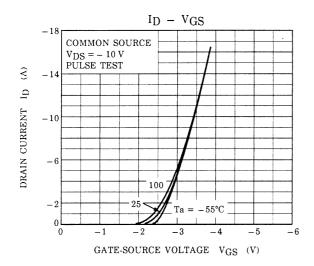
Source-Drain Ratings and Characteristics (Ta = 25°C)

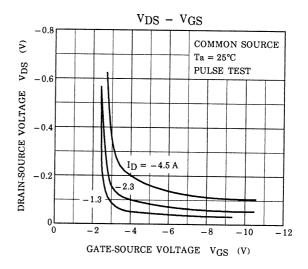
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)		V_{DSF}	I_{DR} = 6 A, V_{GS} = 0 V	1		-1.2	V

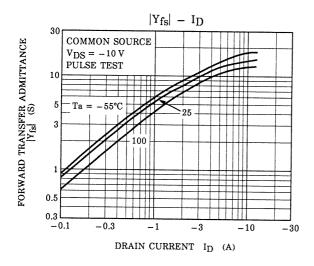
P-ch

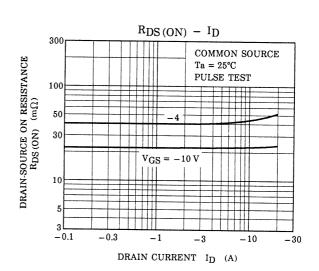




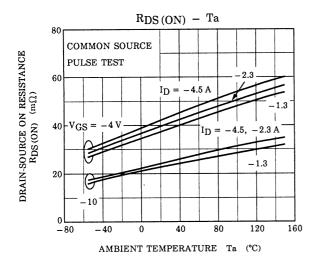


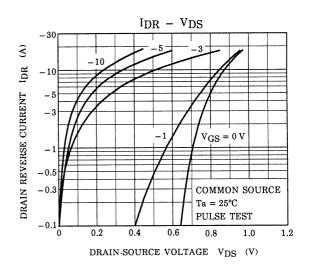


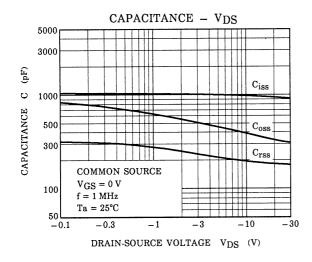


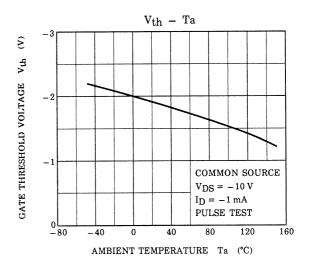


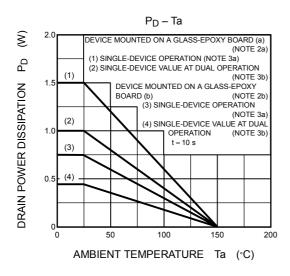
P-ch

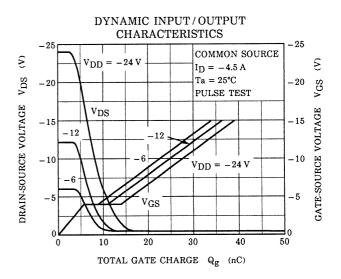




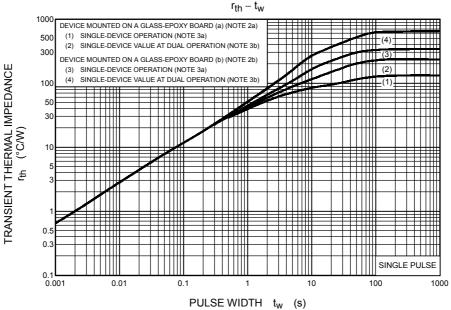


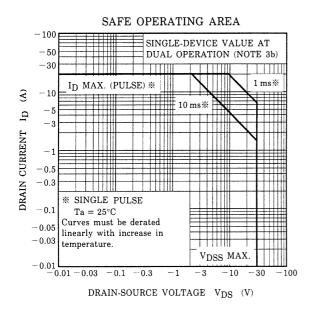


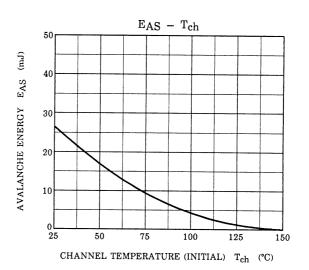




P-ch

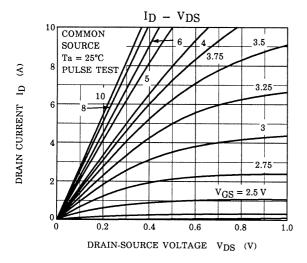


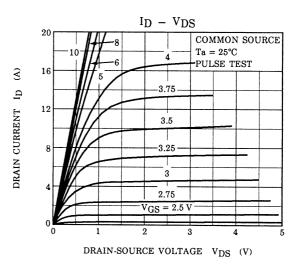


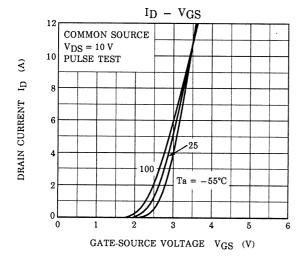


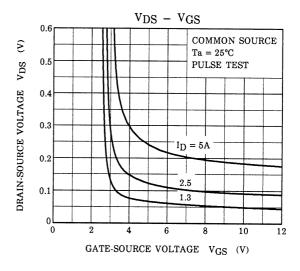
BVDSS 0 V v_{DD} v_{DS} TEST CIRCUIT WAVE FORM

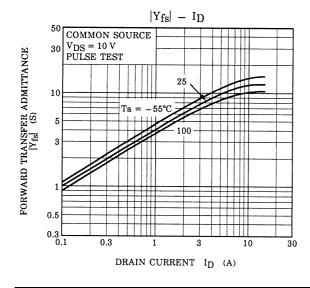
 $T_{ch} = 25^{\circ}\text{C (Initial)}$ Peak IAR = -4.5 A, R_G = 25 Ω EAS = $\frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{BVDSS}{BVDSS - VDD})$ $V_{\mathrm{DD}} = -24 \, \mathrm{V}, \; \mathrm{L} = 1.0 \, \mathrm{mH}$

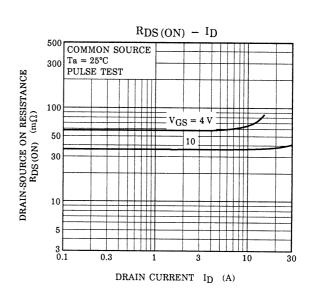


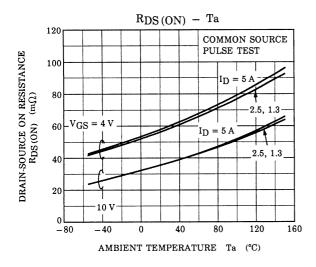


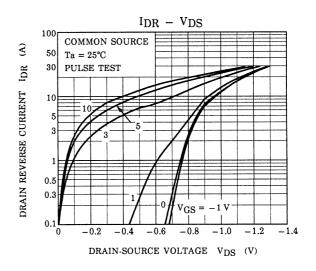


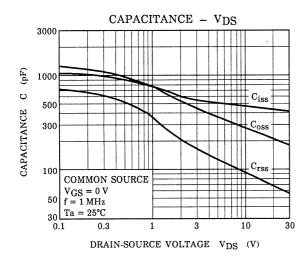


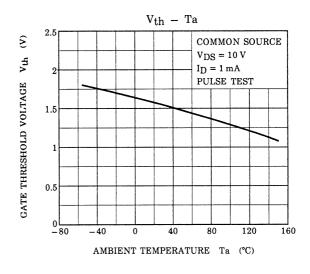


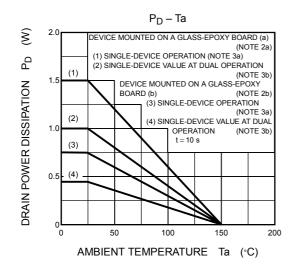


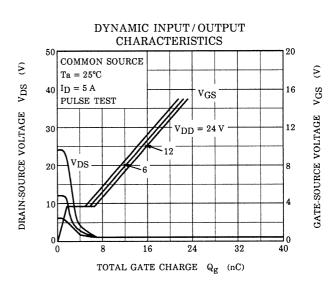


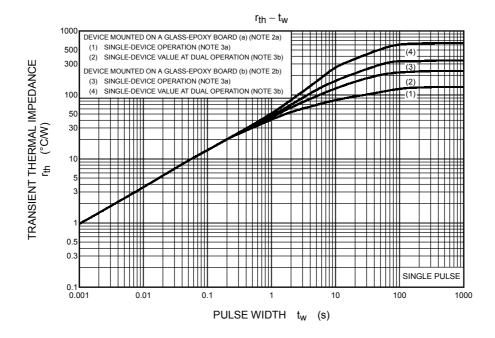


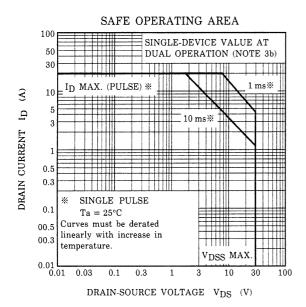


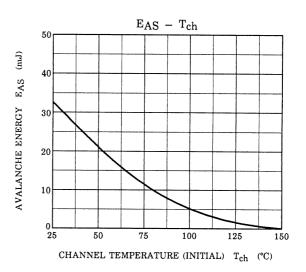


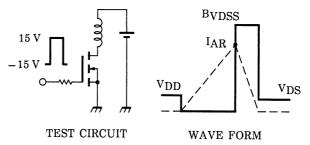












$$\begin{array}{l} T_{ch} = 25^{\circ} C \ (Initial) \\ Peak \ I_{AR} = 5 \ A, \ R_G = 25 \ \Omega \\ V_{DD} = 24 \ V, \ L = 1.0 \ mH \end{array} \\ (\frac{B_{VDSS}}{2} \cdot L \cdot I^2 \cdot (\frac{B_{VDSS}}{2} - V_{DD}) \\ (\frac{B_{VDSS}}{2} - V_{DD}) \\$$

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